PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT7325524

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
JIAN-HSING LEE	04/25/2022
YEH-NING JOU	04/25/2022
CHIH-HSUAN LIN	04/25/2022
CHANG-MIN LIN	04/25/2022
HWA-CHYI CHIOU	04/25/2022

RECEIVING PARTY DATA

Name:	VANGUARD INTERNATIONAL SEMICONDUCTOR CORPORATION
Street Address:	123, PARK AVE-3RD, HSINCHU SCIENCE PARK
City:	HSINCHU
State/Country:	TAIWAN
Postal Code:	30077

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	17741574

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	0941-4735PUS1
NAME OF SUBMITTER:	TAN T. TU
SIGNATURE:	/TAN T. TU/
DATE SIGNED:	05/11/2022

Total Attachments: 2
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ASSIGNMENT

WHEREAS, Jian-Hsing LEE, Yeh-Ning JOU, Chih-Hsuan LIN, Chang-Min LIN, and Hwa-Chyi CHIOU hereafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: PROTECTION CIRCUIT

Filed: 05/11/2022 Serial No. 17/741,574

Executed on: 04/25/2022

WHEREAS, Vanguard International Semiconductor Corporation of 123, Park Ave-3rd, Hsinchu Science Park, Hsinchu, Taiwan 30077, R.O.C hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same;

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, and the entire rights, title and interest in and to any and all foreign patents and applications for any invention described in said U.S. patent applications, in any and all countries foreign to the U.S., including all rights of priority arising from them, and all the rights and privileges under any and all forms of protection, including patents, that may be granted in said countries foreign to the U.S. for them, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Jian-Hsing Lee 4. 25, '22

Jian-Hsing LEE Date

Yeh-Ning Jou 2022. 4. 25.

Yeh-Ning JOU Date

ASSIGNMENT

Chih-Hsuan LIN 2022 4.25

Chih-Hsuan LIN Date

Chang Min Lin 2022.4.25

Chang-Min LIN Date

Hwa-Chyi Chiou 2022.4.25

Hwa-Chyi CHIOU Date